

CLUSTER TOOL SYSTEMS AND METHODS FOR PROCESSING WAFERS

ABSTRACT OF THE DISCLOSURE

The present invention provides exemplary cluster tool systems and methods

- 5 for processing wafers, such as semiconductor wafers. One method includes providing a wafer having initial thickness variations between two wafer surfaces. The wafer is processed (Step 216) through a first module (300), with the first module having apparatus for performing a grinding process, a clean process and a metrology process, all preferably within a clean room environment (310). Wafer processing through the first module includes
- 10 performing the grinding process, clean process and metrology process. The method further includes defining an edge profile on the wafer and processing (Step 222) the wafer through a second module (400).

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